Product Change Notification

Change Notification #: **115974 - 00**

Change Title: **Intel® XWAY™ SmartSLIC PEF41068 SLIC, PCN 115974-00, Manufacturing Site, Activation of Second Manufacturing Site**

Date of Publication: **December 06, 2017**

Key Characteristics of the Change:

Manufacturing Site

Forecasted Key Milestones:

Date of Samples Availability:	December 22, 2017
Date Customer Must be Ready to Receive Post-Conversion Material:	January 06, 2018

**The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

Description of Change to the Customer:

To improve the supply situation for the COSIC Modem Intel activated the existing second source for the assembly for this device. The second source is already fully qualified and used for the production of other product in the same package. We will load the second source with immediately.

1) Functional dimensions and tray stack height remains the same.

The pocket shapes of both trays are the same with exception of the top pocket seating place. That leads to the situation that the two versions are not stackable with each other.

SLIC 120 - PG-VQFN- 48 **PEF41068VV12**	**1st source**	**2nd source**
Source	**JSCC**	**SPIL**
Die Attach Glue		
Leadframe	VQFN sawn type C194 base material	VQFN sawn type C194 base material
External plating	No difference	
Mold Compound	CRM1191AR-A	CRM1191A
Dimensions		
Overall Height	0.9 (max)	0.9 (max)
Standoff	0.04 (max)	0.05(max)
Package Length	7.0 (max)	7.0 (max)
Package Width	7.0 (max)	7.0 (max)

Foot Length	0.5 (max)	0.5 (max)
Lead width	0.28 (max)	0.28 (max)
Lead Pitch	0.5 (max)	0.5 (max)
Comments		
Test Program	Same test program	
Packing Media1)	PEAK TX QFN0707 1.0 1026 6 B	PEAK TX QFN0707 1.0 1026 7 C
Marking	No difference	
Reliability and Quality	Same reliability and quality level	
Ordering	Same IPN	

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers for this change. The device from the second source will have the same IPN. Customers should notify their receiving department of the additional country which will be providing the Test/Finish on the products. It possible that Customers may receive a mix of material from both sites.

Customers may contact their Intel Field Sales Representative or the contacts listed on the last page of this Product Change Notification appropriate to your geo with questions.

Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Product Code	S-Spec	MM#
Intel® XWAY™ SmartSLIC PEF41068 SLIC	A2	PEF41068VV12	S LL8U	946825

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
December 6, 2017	00	Originally Published PCN

Product Change Notification
115974 - 00

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

A "Mission Critical Application" is any application in which failure of the Intel Product could result, directly or indirectly, in personal injury or death. SHOULD YOU PURCHASE OR USE INTEL'S PRODUCTS FOR ANY SUCH MISSION CRITICAL APPLICATION, YOU SHALL INDEMNIFY AND HOLD INTEL AND ITS SUBSIDIARIES, SUBCONTRACTORS AND AFFILIATES, AND THE DIRECTORS, OFFICERS, AND EMPLOYEES OF EACH, HARMLESS AGAINST ALL CLAIMS COSTS, DAMAGES, AND EXPENSES AND REASONABLE ATTORNEYS' FEES ARISING OUT OF, DIRECTLY OR INDIRECTLY, ANY CLAIM OF PRODUCT LIABILITY, PERSONAL INJURY, OR DEATH ARISING IN ANY WAY OUT OF SUCH MISSION CRITICAL APPLICATION, WHETHER OR NOT INTEL OR ITS SUBCONTRACTOR WAS NEGLIGENT IN THE DESIGN, MANUFACTURE, OR WARNING OF THE INTEL PRODUCT OR ANY OF ITS PARTS.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined". Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com
Asia Pacific/PRC Contact: apacgccb@intel.com
Europe Email: eccb@intel.com
Japan Email: jccb.ijkk@intel.com

Copyright © Intel Corporation 2017. Other names and brands may be claimed as the property of others.

3D XPoint, Axxia, Basis, Basis Peak, BlueMoon, BunnyPeople, Celeron, Centrino, Cilk, Curie, Flexpipe, Intel, the Intel logo, Intel Atom, Intel CoFluent, Intel Core, Intel. Experience What's Inside, the Intel. Experience What's Inside logo, Intel Inside, the Intel Inside logo, Intel Insider, Intel Joule, Intel RealSense, Intel SingleDriver, Intel SpeedStep, Intel Unite, Intel vPro, Intel Xeon Phi, Intel XScale, InTru, the InTru logo, the InTru Inside logo, InTru soundmark, Iris, Itanium, MCS, MMX, Optane, Ostro, Pali, Pentium, picoArray, Picochip, picoXcell, Puma, Quark, SMARTi, Soletta, Sound Mark, StarPro, Stay With It, the Engineering Stay With It logo, StreamSight, Tarari, The Journey Inside, Thunderbolt, the Thunderbolt logo, Transcede, True Key, Ultrabook, VTune, Xeon, X-GOLD, XMM, X-PMU and XPOSYS are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries.

Microsoft, Windows, and the Windows logo are trademarks, or registered trademarks of Microsoft Corporation in the United States and/or other countries. Java is a registered trademark of Oracle and/or its affiliates. Bluetooth is a trademark owned by its proprietor and used by Intel Corporation under license. Intel Corporation uses the Palm OS* Ready mark under license from Palm, Inc. OpenCL and the OpenCL logo are trademarks of Apple Inc. used by permission by Khronos. Learn how to use Intel Trademarks and Brands correctly at http://www.intel.com/intel/legal/tmusage2.htm.